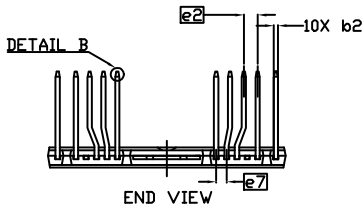
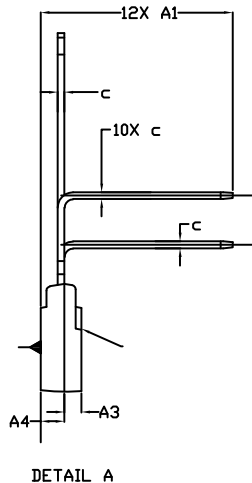
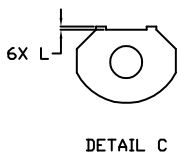
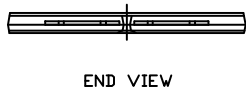
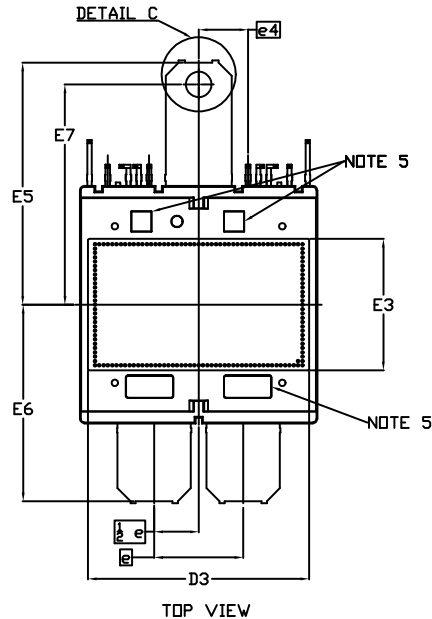
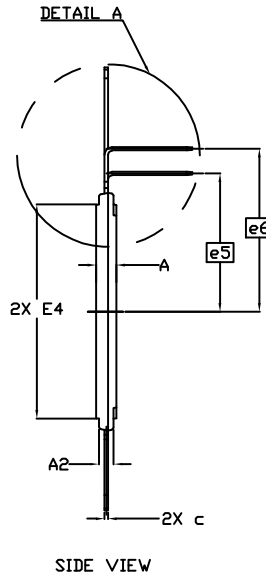
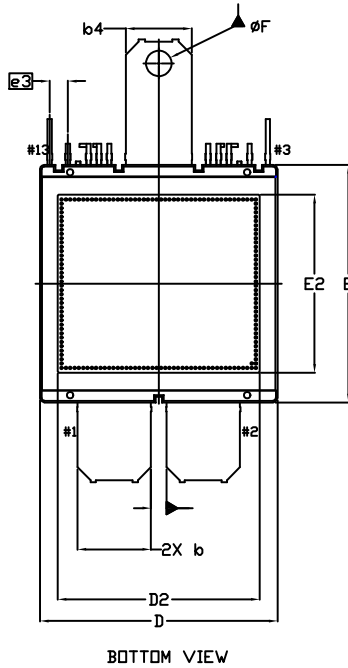


AHPM13-CGA MODULE
CASE MODHR
ISSUE B

DATE 19 MAY 2023



- NOTES:
1. DIMENSIONING AND TOLERANCING PER. ASME Y14.5M, 2009.
 2. CONTROLLING DIMENSION: MILLIMETERS
 3. DIMENSIONS D & E DO NOT INCLUDE MOLD PROTRUSIONS
 4. DIMENSIONS b, b1, b2 DO NOT INCLUDE DAMBAR REMAIN.
 5. MARKING AREA.
 6. ALTERNATE PACKAGE DIMENSIONING OPTION AVAILABLE IN DDC# 08ADN34464H



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	4.65	4.70	4.75
A1	21.55	22.25	22.95
A2	3.20	3.40	3.60
A3	1.95 REF		
A4	2.75 REF		
b	16.70	17.00	17.30
b2	0.90	1.00	1.10
b3	0.50 REF		
b4	15.20	15.30	15.40
c	0.70	0.80	0.90
D	54.80	55.00	55.20
D2	45.80	46.80	47.80
D3	50.50	51.20	51.90
E	54.80	55.00	55.20
E2	40.20	41.20	42.20

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
E3	29.80	30.50	31.20
E4	49.40	49.60	49.80
E5	55.65	56.00	56.35
E6	45.15	45.50	45.85
E7	50.75	51.00	51.25
e	20.60 BSC		
e2	3.20 BSC		
e3	4.20 BSC		
e4	11.45 BSC		
e5	32.00 BSC		
e6	37.70 BSC		
e7	2.40 BSC		
F	5.90	6.00	6.10
L	0.50 REF		
M*	10* REF		

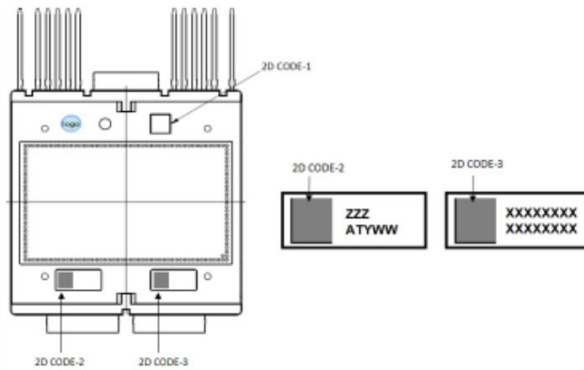
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DESCRIPTION:	AHPM13-CGA MODULE	PAGE 1 OF 2

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**AHPM13-CGA MODULE
CASE MODHR
ISSUE B**

DATE 19 MAY 2023

**GENERIC
MARKING DIAGRAM***



ZZZ = Assembly Lot Code
 AT = Assembly & Test Location
 Y = Year
 WW = Work Week
 XXXX = Specific Device Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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